

6-5330808-5 ✓ ACTIVE

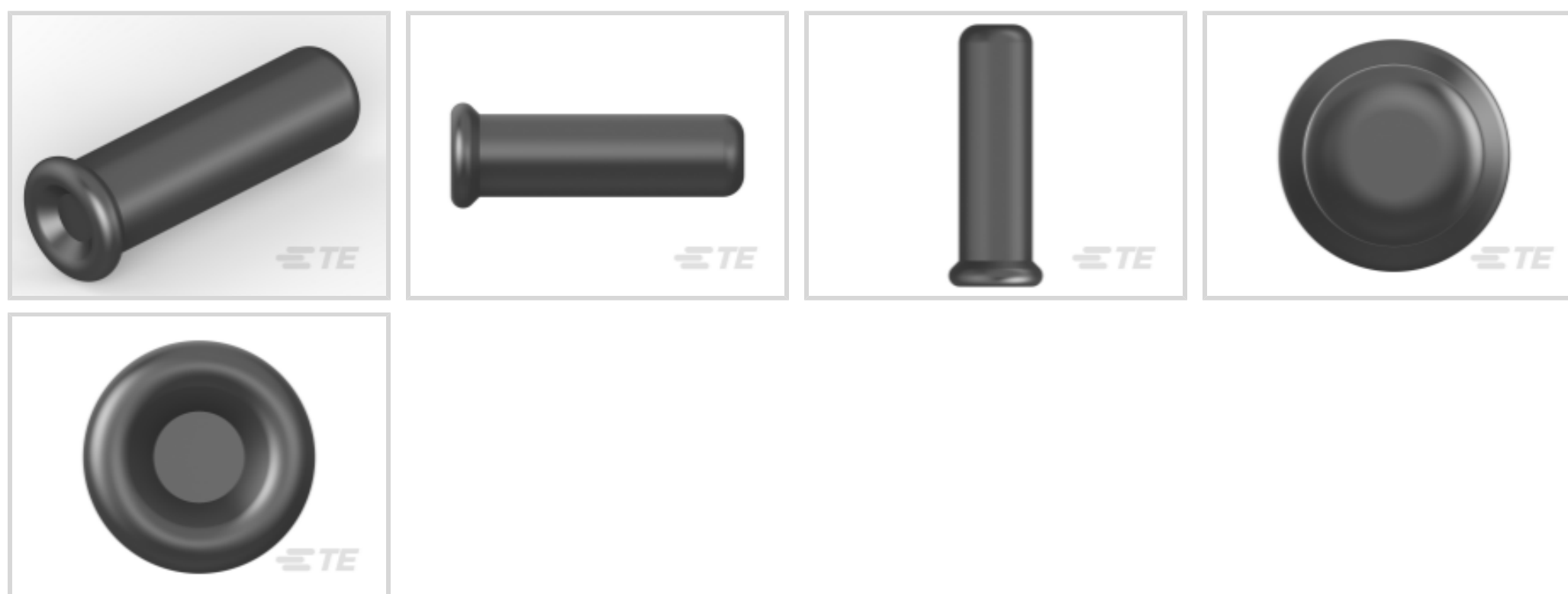
TE Internal #: 6-5330808-5

Socket Length 3.61 mm [.142 in], PCB Hole Diameter 1.04 mm [.041 in], Closed Bottom, .081 – .162 mm² Wire Size, 28 – 25 AWG Wire Size, Pin Sockets

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Connectors > Socket Connectors > Pin Sockets > Mini Spring Sockets: Closed Bottom, 3A



Socket Length: 3.61 mm [.142 in]

PCB Hole Diameter: 1.04 mm [.041 in]

Socket Sleeve Style: Closed Bottom

Wire Size: .081 – .162 mm²

[All Mini Spring Sockets: Closed Bottom, 3A \(10\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Socket Sleeve Style	Closed Bottom
Connector System	Cable-to-Board
Sealable	No

Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
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Body Features

Sleeve Material	Copper
Sleeve Plating Material	Tin

Contact Features

Contact Spring Plating Material	Gold
Contact Spring Plating Thickness	.762 μm[30 μin]
Contact Mating Area Plating Material Thickness	30 μm[30 μin]
Contact Mating Area Plating Material	Gold



Contact Base Material	Beryllium Copper
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Contact Current Rating (Max)	3 A
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Termination Features

Insertion Method	Hand/Semi-Automatic
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Termination Method to PCB	Through Hole - Press-Fit
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Termination Method to Wire & Cable	Solder
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Dimensions

PCB Thickness (Recommended)	.79 – 3.18 mm [.031 – .125 in]
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Socket Length	3.61 mm [.142 in]
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PCB Hole Diameter	1.04 mm [.041 in]
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Wire Size	.081 – .162 mm ²
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Mating Pin Diameter Range	.33 – .51 mm [.013 – .02 in]
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Usage Conditions

Operating Temperature Range	-65 – 125 °C [-85 – 257 °F]
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Operation/Application

Solder Process Feature	None
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Circuit Application	Signal
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Packaging Features

Packaging Quantity	2000
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Packaging Method	Bag, Loose Piece
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Other

Spring Material	Beryllium Copper
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Pin-in-Paste capable to 260°C
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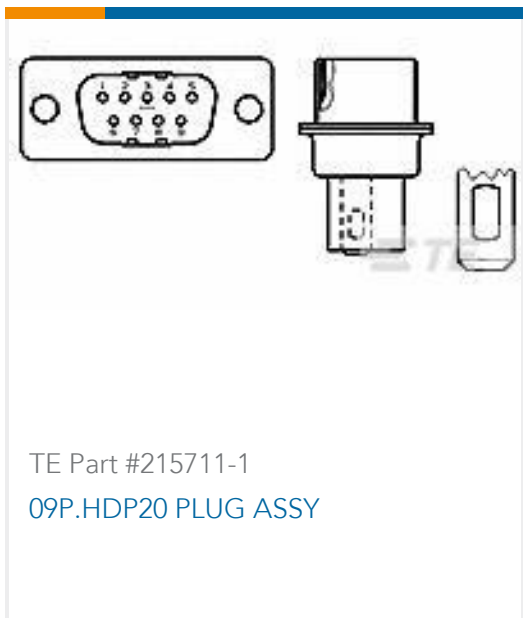
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought





Documents

Product Drawings

[SOCKET,MIN-SPR SN-AU SER-1](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_6-5330808-5_O.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-5330808-5_O.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-5330808-5_O.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Product Specification](#)

English